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Patent and Trademark Office

ATTORNEY DOCKET NO.:

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural name are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

PRESSURE-SENSITIVE ADHESION SHEETS FOR SILICONE OXIDE-CONTAINING
MATERIAL

the specification of which:

is attached hereto; or

was filed as United States application Serial No. _____ on _____ and was amended on _____ (if applicable); or

was filed as PCT international application Number _____ on _____ and was amended under PCT Article 19
on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the U.S. Patent and Trademark Office information which is material to the patentability of claims presented in this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119(a)-(d) or §365(b) of any foreign application(s) for patent or inventor's certificate or §365(a) of any PCT international application(s) designating at least one country other than the United States of America listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed:

PRIOR FOREIGN APPLICATION(S):

COUNTRY (if PCT, indicate PCT)	APPLICATION NUMBER	DATE OF FILING (day, month, year)	PRIORITY CLAIMED
Japan	P. Hei. 9-346124	16, 12, 1997	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
Japan	P. Hei. 9-353102	22, 12, 1997	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
			<input type="checkbox"/> Yes <input type="checkbox"/> No
			<input type="checkbox"/> Yes <input type="checkbox"/> No

I hereby claim the benefits under Title 35, United States Code §119(e) of any United States provisional application(s) listed below.

U.S. PROVISIONAL APPLICATIONS

U.S. PROVISIONAL APPLICATION NO.	U.S. FILING DATE

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) or §365(c) of any PCT international application(s) designating the United States of America that is/are listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in that/those prior application(s) in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to the patentability of claims presented in this application in accordance with Title 37, Code of Federal Regulations, §1.56 which became available between the filing date of the prior application(s) and the national or PCT international filing date of this application:

PRIOR U.S. APPLICATIONS OR PCT INTERNATIONAL APPLICATIONS DESIGNATING THE U.S. FOR BENEFIT

U.S. APPLICATIONS		STATUS (Check One)		
U.S. APPLICATION NO.	U.S. FILING DATE	PATENTED	PENDING	ABANDONED

POWER OF ATTORNEY: As a named inventor, I hereby appoint the registered practitioners of Morgan, Lewis & Bockius LLP included in the Customer Number provided below to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and direct that all correspondence be addressed to that Customer Number.

Customer Number: 009629

Direct Telephone Calls To:
(name and telephone number)

J. Michael Thesz
202-467-7658

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

FULL NAME OF SOLE OR FIRST INVENTOR	Katsunari Oji	
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FIRST OR SOLE INVENTOR'S SIGNATURE	<i>Katsunari Oji</i>	DATE December 9, 1999
FULL NAME OF SECOND INVENTOR	Yoshinao Kitamura	
RESIDENCE & CITIZENSHIP	Osaka, Japan	COUNTRY OF CITIZENSHIP Japan
POST OFFICE ADDRESS	c/o NITTO DENKO CORPORATION, 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka, Japan	
SECOND INVENTOR'S SIGNATURE	<i>Yoshinao Kitamura</i>	DATE December 9, 1999
FULL NAME OF THIRD INVENTOR	Takao Yoshikawa	
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THIRD INVENTOR'S SIGNATURE	<i>Takao Yoshikawa</i>	DATE December 9, 1999

Listing of Inventors Continued on attached page(s) ☐ Yes ☒ No

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

PRESSURE-SENSITIVE ADHESION SHEETS FOR SILICONE OXIDE-CONTAINING MATERIAL

for which I/WE executed an application for United States Letters Patent concurrently herewith; or on December 9, 1998; or filed an application for United States Letters Patent on _____, (Serial No. _____); and

WHEREAS, NITTO DENKO CORPORATION,
a corporation of Japan, whose post office address is
1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka, Japan (hereinafter referred to as Assignee),
is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

1. Full Name of Sole of First Assignor Katsunari Oji	Assignor's Signature <i>Katsunari Oji</i>	Date December 9, 1998
Address Osaka, Japan		Citizenship Japan
2. Full Name of Second Assignor Yoshinao Kitamura	Assignor's Signature <i>Yoshinao Kitamura</i>	Date December 9, 1998
Address Osaka, Japan		Citizenship Japan

MORGAN, LEWIS & BOCKIUS